

Product / Package Information	
Package	SOT23
Body Size	
Lead Count	6
Terminal Finish	NiPdAu

Environmental Compliance Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

### Materials Declaration

#### Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.09 E-03	87.3	873000	41.31	413098
Thermosets	Phenol Resin	Proprietary	3.65 E-04	4.5	45000	2.13	21294
Thermosets	Epoxy Resin 1	Proprietary	2.44 E-04	3.0	30000	1.42	14196
Thermosets	Epoxy Resin 2	Proprietary	2.44 E-04	3.0	30000	1.42	14196
Others	Others	Proprietary	1.62 E-04	2.0	20000	0.95	9464
Other inorganic materials	Carbon Black	1333-86-4	1.62 E-05	0.2	2000	0.09	946
Subtotal			8.12 E-03	100.0	1000000	47	473193

#### Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	7.52 E-03	97.5	975000	43.80	437982
Copper & its alloys	Iron	7439-89-6	1.81 E-04	2.35	23500	1.06	10556
Copper & its alloys	Zinc	7440-66-6	9.25 E-06	0.12	1200	0.05	539
Copper & its alloys	Phosphorus	7723-14-0	2.31 E-06	0.03	300	0.01	135
Subtotal			7.71 E-03	100	1000000	45	449192

#### Internal/External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	8.35 E-05	90.91	909091	0.49	4867
Precious metals	Palladium	7440-05-3	7.26 E-06	7.91	79051	0.04	423
Precious metals	Gold	7440-57-5	1.09 E-06	1.19	11858	0.01	63
Subtotal			9.19 E-05	100.00	1000000	0.54	5354

#### Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.70 E-04	99.99	1000000	0.99	9907

#### Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.00 E-03	100	1000000	5.83	58275

#### Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon Dioxide	14808-60-7	3.49 E-05	49.9	499000	0.20	2036
Organic materials	Reaction product: bisphenol-F-(epichlorhydrin); epoxy resin (number average molecular weight <= 700)	9003-36-5	1.40 E-05	20	200000	0.08	816
Organic materials	1,4-bis(2,3-epoxypropoxy)butane	2425-79-8	1.40 E-05	20	200000	0.08	816
Others	Aromatic Amine	Proprietary	3.50 E-06	5	50000	0.02	204
Glass	Glass	65997-17-3	3.50 E-06	5	50000	0.02	204
Organic materials	Reaction product: bisphenol-A-(epichlorhydrin); epoxy resin (number average molecular weight <= 700)	25068-38-6	7.00 E-08	0.1	1000	0.00	4
Subtotal			7.00 E-05	100	1000000	0.41	4079

Package Totals	Weight (g)	Percentage (%)	PPM
	1.72 E-02	100	1000000

Vontrol ID: MS011611PKG3456

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



AHEAD OF WHAT'S POSSIBLE™

ADI Proprietary